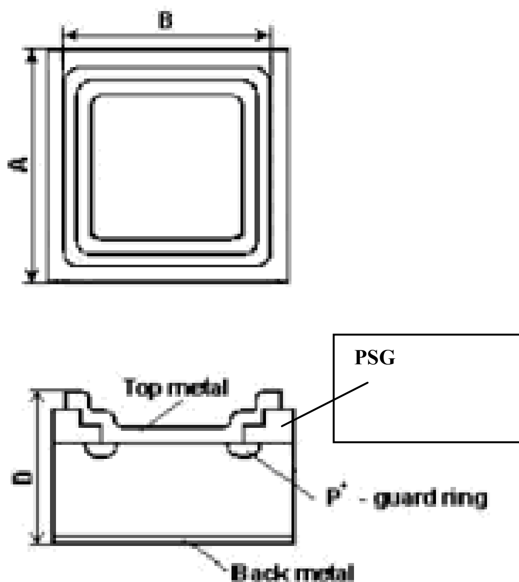
SCHOTTKY DIODES KDS- 02015E.

PRELIMINARY.

Oct. 2012.

VSP-MIKRON	2A/15V. Die Size-45mil.			
Electrical Characteristics	**Symbol**	**Unit**	**Spec. limit**	**Die Sort**
Breakdown Voltage @ I_R=10mA	V_B	V	15	20
Average Rectified Forward Current	$I_{F(AV)}$	A	2,0	-
DC Forward Voltage @ 25˚C, I_F=2,0A	V_F	V	0,42	0,4
Maximum Reverse Current @ 25˚C, V_R=20V 25˚C, V_R=15V 100˚C, V_R=15V	I_R	MA	- 0,800 50,0	0,800 0,600 40,0
Peak Forward Surge Current 8,3ms single half sine-wave superimposed on rated load (JEDEC METHOD)	I_{FSM}	A	50	-
Peak Repetitive Reverse Surge Current @2,0µs, f=1kHz., T_J<150˚C.	I_{RRM}	A	2,0	
Electrostatic Discharge Voltage. JEDEC Method. ESD HBM. Contact.	ESD	kV	±8 (contact)	
Voltage Rate of Change	dV/dt	V/µS	10.000	
Operating Junction Temperature	T_J	˚C	125	



DIM	ITEM	µm
A_X A_y	Die Size	1150 1150
B_X B_y	Top Metal Size	1030 1030
D	Thickness	300max.
Scribe line Width		80

Top metal: a) **Al** – for Wire Bonding;

b) ***Al-Ni-Ag*** – for Soldering.

Backside metal: ***Ti-Ni-Ag***.

www.vsp-mikron.com